

# Liang He

Assistant Professor, Department of Computer Science

Director, Design and Engineering for Making (DE4M) Lab

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## Research Interests

The primary focus of my research in Human-Computer Interaction (HCI) is digital fabrication, aiming to enable customizable and personalized experiences through new pipelines, techniques, and devices that integrate computational and physical intelligence. In my research, I emphasize prototyping and tinkering as processes to explore how people might interact with the physical world across diverse domains, including making, haptics, accessibility, and education. The current research directions include:

- Computational design and AI-assisted tools for creative tasks
- Streamlined making pipelines for personal fabrication
- Intelligent physical agents for human body-centered and environmental-scale interfacing and interaction

## Employment

8/2025 **Assistant Professor (tenure-track)**

*University of Texas at Dallas, Department of Computer Science  
Director of Design & Engineering for Making (DE4M) Lab*

6/2025–8/2025 **Visiting Associate Professor**

*Keio University, Department of Information and Computer Science  
Hosted by Prof. Koya Narumi*

8/2022–5/2025 **Assistant Professor (tenure-track)**

*Purdue University, Department of Computer Graphics Technology*

10/2020–12/2020 **Research Intern with Kris J. Erickson and Rafael 'Tico' Ballagas**  
*3D Print Lab, HP Labs, Palo Alto, CA*

6/2019–9/2019 **Research Intern with Rafael 'Tico' Ballagas**

*Artificial Intelligence & Emerge Computing Lab, HP Labs, Palo Alto, CA*

6/2016–8/2016 **Research Intern** with Rob DeLine and Saleema Amershi  
*Microsoft Research, Redmond, WA*

5/2014–8/2014 **Research Intern** with Ellen Yi-Luen Do and Beryl Plimmer  
*Keio-NUS CUTE Center, Singapore*

## Education

8/2022 **Ph.D., Computer Science & Engineering**, *University of Washington, Seattle*  
 Dissertation: Fabricating Kinetic Objects with 3D Printable Spring-Based Mechanisms for Interactivity  
 Advisor: Jon E. Froehlich  
 Committee members: Jennifer Mankoff, Adriana Schulz, and Nadya Peek  
*(Transferred from the University of Maryland, College Park to UW in 2017)*

5/2015 **M.S., Computational Design**, *Carnegie Mellon University, Pittsburgh*  
 Thesis: Squeezapulse - Adding Interactive Input Using Passive Pulses of Air

5/2013 **M.S., Computer Science and Technology**, *University of Chinese Academy of Sciences*  
 Thesis: A Tangible Approach for Storytelling

5/2010 **B.Eng, Software Engineering**, *Beihang University (BUAA)*

## Publications

*My students and myself are underlined.*

### Conference Papers

2026 [C.18] **Not Seeing the Whole Picture: Challenges and Opportunities in Using AI for Co-Making Physical, DIY-AT for People with Visual Impairments.** Ben Kosa, Hsuanling Lee, Jasmin Li, Sanbrita Mondal, Yuhang Zhao, and Liang He. *To appear at CHI '26.*

2026 [C.17] **AgentCoach: LLM-Based Adaptive Coaching Feedback for Motor Skill Learning.** Dizhi Ma, Jiakun Yu, Xinyi Wang, Xiyun Hu, Liang He, Sooyeon Jeong, and Karthik Ramani. *To appear at CHI '26.*

2026 [C.16] **FluxLab: Creating 3D Printable Shape-Changing Devices with Integrated Deformation Sensing.** Hsuanling Lee, Jiakun Yu, Shurui Zheng, Te-Yen Wu, and Liang He. *To appear at TEI '26.*

2025 [C.15] **4D Leaf Circuits: Integrating Self-folding Origami and Conductive Leaf Transfer for Freeform Circuits.** Yutaro Nakaya\*, Ko Fujino\*, Liang He, and Koya Narumi. In *Proceedings of the ACM Symposium on Computational Fabrication (SCF '25)*.

2025 [C.14] **3Duino: A Low-Barrier Platform for Prototyping Interactive 3D-Printed Devices.** Yonghao Shi, Zejia Cai, Liuyi Chen, Yuning Su, Liang He, Xing-Dong Yang, and Te-Yen Wu. In *Proceedings of the ACM Symposium on Computational Fabrication (SCF '25)*.

2025 [C.13] **A11yShape: AI-Assisted 3-D Modeling for Blind and Low-Vision Programmers.** Zhuohao (Jerry) Zhang, Haichang Li, Chun Meng Yu, Faraz Faruqi, Junan Xie, Gene S-H Kim, Mingming Fan, Angus Forbes, Jacob O. Wobbrock, Anhong Guo, and Liang He. In *Proceedings of the 27th International ACM SIGACCESS Conference on Computers and Accessibility (ASSETS '25)*.

2025 [C.12] **"I Want to Use Technology to Help Farmers in the Future": Enhancing Children's Understanding of Farming through Tangible User Interfaces and Embodied Interaction.** Yili Wen, Jiaxin Wang, Hongni Ye, Liang He, Min Fan, Xin Tong. In *Proceedings of the 24th Annual ACM Interaction Design and Children Conference (IDC '25)*.

2024 [C.11] **MobiPrint: A Mobile 3D Printer for Environment-Scale Design and Fabrication.** Daniel Campos Zamora, Liang He, and Jon E. Froehlich. In *Proceedings of the 37th Annual ACM Symposium on User Interface Software and Technology (UIST '24)*.

2023 [C.10] **3D Printing Magnetophoretic Display.** Zeyu Yan, Hsuanling Lee, Liang He, and Huaishu Peng. In *Proceedings of the 36th Annual ACM Symposium on User Interface Software and Technology (UIST '23)*.

2022 [C.9] **Kinergy: Creating 3D Printable Motion using Embedded Kinetic Energy.** Liang He, Xia Su, Huaishu Peng, Jeffrey I. Lipton, and Jon E. Froehlich. In *Proceedings of the 35th Annual ACM Symposium on User Interface Software and Technology (UIST '22)*.

[C.8] **FlexHaptics: A Design Method for Haptic Inputs Using Flat Compliant Structures.** Hongnan Lin, Liang He, Fangli Song, Yifan Li, Tingyu Chen, Clement Zheng, Wei Wang, and HyunJoo Oh. In *Proceedings of the 40th Annual ACM Conference on Human Factor in Computing Systems (CHI '22)*.

2021 [C.7] **HulaMove: Using Commodity IMU for Waist Interaction.** Xuhai Xu, Jiahao Li, Tianyi Yuan, Liang He, Xin Liu, Yukang Yan, Yuntao Wang, Yuanchun Shi, Jennifer Mankoff, and Anind K. Dey. In *Proceedings of the 39th Annual ACM Conference on Human Factors in Computing Systems (CHI '21)*.

2019 [C.6] **Ondulé: Designing and Controlling 3D Printable Springs.** Liang He, Huaishu Peng, Michelle Lin, Ravikanth Konjeti, François Guimbretière, and Jon E. Froehlich. In *Proceedings of the 32nd Annual ACM Symposium on User Interface Software and Technology (UIST '19)*.

2017 [C.5] **MakerWear: A Tangible Approach to Interactive Wearable Creation for Children.** Majeed Kazemitaar, Jason McPeak, Alexander Jiao, Liang He, Thomas Outing, and Jon E. Froehlich. In *Proceedings of the 35th annual ACM conference on Human factors in computing systems (CHI '17)*.  
 **Best Paper Award [Top 1%]**

[C.4] **SqueezePulse: Adding Interactive Input to Fabricated Objects Using Corrugated Tubes and Air Pulses.** Liang He, Gierad Laput, Eric Brockmeyer, and Jon E. Froehlich. In *Proceedings of the ACM symposium on tangible and embodied interaction (TEI '17)*.

2015 [C.3] **PneuHaptic: Delivering Haptic Cues with a Pneumatic Armband.** Liang He, Cheng Xu, Ding Xu, and Ryan Brill. In *Proceedings of the 19th International Symposium on Wearable Computers (ISWC '15)*.

[C.2] **CozyMaps: Real-time Collaboration on a Shared Map with Multiple Displays.** Kelvin Cheng, Liang He, Xiaojun Meng, David A. Shamma, Dung Nguyen, and Anbarasan Thangapalam. In *Proceedings of the 17th International Conference on Human-Computer Interaction with Mobile Devices and Services (MobileHCI'15)*.

[C.1] **New Interaction Tools for Preserving an Old Language.** Beryl Plimmer, Liang He, Tariq Zaman, Kasun Karunanayaka, Alvin W. Yeo, Garen Jengan, Rachel Blagojevic, and Ellen Yi-Luen Do. In *Proceedings of the 33rd annual ACM conference on Human factors in computing systems (CHI '15)*.  
 **Honorable Mentions Award [Top 3%]**

## Journal Papers

2026 [J.3] **SafetyBuilder: A Framework of In-situ AI-assisted Creation of Child Safety Protection.** Jiawei Li, Zisu Li, Siyu Chen, Ziyan Wang, Yukai Zhang, Mingming Fan, and Liang He. *To publish at IMWUT and appear at UbiComp '26*.

2021 [J.2] **ModElec: A Design Tool for Prototyping Physical Computing Devices Using Conductive 3D Printing.** Liang He, Jarrid A. Wittkopf, Ji Won Jun, Kris Erickson, and Rafael 'Tico' Ballagas. In *Proceedings of the ACM on Interactive, Mobile, Wearable and Ubiquitous Technologies (IMWUT)* 5, no. 4 (2021): 1-20.

2014 [J.1] **StoryCube: Supporting Children's Storytelling with a Tangible Tool.** Danli Wang, Liang He, and Keqin Dou. *The Journal of Supercomputing*, Volume 70 Issue 1, Pages 269-283. Springer. 2014.

## Dissertation & Doctoral Position Paper

2022 [Diss.] **Fabricating Kinetic Objects with 3D Printable Spring-Based Mechanisms for Interactivity.** Liang He. University of Washington, 2022.

2020 [DC.1] **Designing, Controlling, and Fabricating In-Place Augmented Structures.** Liang He. In *Adjunct Proceedings of the 33rd Annual ACM Symposium on User Interface Software and Technology (UIST '20 Doctoral Symposium)*. Committee: Michel Beaudouin-Lafon, Ranjitha Kumar, Pedro Lopes, Camille Moussette, Ken Hinckley

## ***Extended Abstracts/Poster& Workshop Papers***

2026 [W.2] **Everyday Wearable for Personalized Health and Well-Being.** Chankyu (Charlie) Han, Hongyu Mao, Qiuyue (Shirley) Xue, Ishan Chatterjee, Liang He, Xuhai Xu, Junyi Zhu, and Yiyue Luo. *To appear at CHI '26*.

2026 [P.11] **PuffFab: Making Shape Transformable Rice Paper for Playful Food Fabrication.** Yili Wen, Yafei Ge, Xin Tong, and Liang He. *To appear at TEI '26*.

2025 [W.1] **Towards Rapid Fabrication of Custom Tactile Surface Indicators for Indoor Navigation.** Daniel Campos Zamora, Liang He, and Jon E. Froehlich. In *Proceedings of the 26th International ACM SIGACCESS Conference on Computers and Accessibility (ASSETS '24)*.

2024 [P.10] **Fluxable: A Tool for Making 3D Printable Sensors and Actuators.** Hsuanling Lee, Yujie Shan, Huachao Mao, and Liang He. In *Adjunct Proceedings of the 37th Annual ACM Symposium on User Interface Software and Technology (UIST Adjunct '24)*.  
 **Best Poster Award [Top 1%]**

[P.9] **3D Printing Shape-Changing Devices with Inductive Sensing.** Hsuanling Lee and Liang He. In *ACM SIGGRAPH 2024 Posters (SIGGRAPH '24)*.

2023 [P.8] **A Multi-modal Toolkit to Support DIY Assistive Technology Creation for Blind and Low Vision People.** Liwen He, Yifan Li, Mingming Fan, Liang He, and Yuhang Zhao. In *Adjunct Proceedings of the 36th Annual ACM Symposium on User Interface Software and Technology (UIST '23 Adjunct)*.

[P.7] **Understanding the Experiences, Challenges, and Needs of Dementia Caregivers in the Indian Subcontinent.** Srishti Shekhar Agrawal, Shrey Panchal, and Liang He. In *the 25th International ACM SIGACCESS Conference on Computers and Accessibility (ASSETS '23)*.

2022 [D.1] **sPrintr: Towards In-Situ Personal Fabrication using a Mobile 3D Printer.** Daniel Campos Zamora, Liang He, Yueqian Zhang, Xuhai Xu, Jennifer Mankoff, and Jon E. Froehlich. In *Symposium on Computational Fabrication (SCF '22)*.

[SIG.1] **SIG: Towards More Personal Health Sensing.** Junyi Zhu, Liang He, Jun Nishida, Hamid Ghaednia, Cindy Hsin-Liu Kao, Jon E. Froehlich, Edward Jay Wang, and Stefanie Mueller. In *Extended Abstracts of the 2022 CHI Conference on Human Factors in Computing Systems (CHI EA '22)*.

2020 [EA.3] **PneuFetch: Supporting Blind and Visually Impaired People to Fetch Nearby Objects via Light Haptic Cues.** Liang He, Ruolin Wang, Xuhai Xu. In *Proceedings of CHI '20 Extended Abstracts on Human Factors in Computing Systems (CHI EA '20)*.

2019 [P.6] **A Multi-Modal Approach for Blind and Visually Impaired Developers to Edit Webpage Designs.** Venkatesh Potluri, Liang He, Christine Chen, Jon E. Froehlich, and Jennifer Mankoff. In *the 21st International ACM SIGACCESS Conference on Computers and Accessibility (ASSETS '19)*.

2017 [P.5] **TacTILE: A Preliminary Toolchain for Creating Accessible Graphics with 3D-Printed Overlays and Auditory Annotations.** Liang He, Zijian Wan, Leah Findlater, and Jon E. Froehlich. In *Poster Proceedings of the 19th International ACM SIGACCESS Conference on Computers & Accessibility (ASSETS '17)*.

[P.4] **Designing 3D-Printed Deformation Behaviors Using Spring-Based Structures: An Initial Investigation.** Liang He, Huaishu Peng, Joshua Land, Mark D. Fuge, and Jon E. Froehlich. In *Adjunct Proceedings of the 30th Annual ACM Symposium on User Interface Software and Technology (UIST '17)*.

[P.3] **Early Exploration of Deformable Interactive Designs with 3D-Printed Springs.** Liang He, Joshua Land, Huaishu Peng, Mark D. Fuge, and Jon E. Froehlich. In *Proceedings of the 1st Annual ACM Symposium on Computational Fabrication (SCF '17)*.

2016 [EA.2] **ReWear: Early Explorations of a Modular Wearable Construction Kit for Young Children.** Majeed Kazemitaab, Liang He, Katie Wang, Chloe Aloimonos, Tony Cheng, and Jon E. Froehlich. In *Proceedings of CHI '16 Extended Abstracts on Human Factors in Computing Systems (CHI EA '16)*.  
 **Best Poster Award [Top 1%]**

[EA.1] **VRSurus: Enhancing Interactivity and Tangibility of Puppets in Virtual Reality.** Ruofei Du and Liang He. In *Proceedings of CHI '16 Extended Abstracts on Human Factors in Computing Systems (CHI EA '16)*.

2012 [P.2] **E-Block: A Tangible Programming Tool for Children.** Danli Wang, Yang Zhang, Tianyuan Gu, Liang He, and Hongan Wang. In *Adjunct Proceedings of the 25th Annual ACM Symposium on User Interface Software and Technology (UIST '12)*.

[P.1] **TempoString: A Tangible Tool for Children's Music Creation.** Liang He, Guang Li, Yang Zhang, Danli Wang, and Hongan Wang. In *Proceedings of the 14th International Conference on Ubiquitous Computing (UbiComp '12)*.

## Funding

2024 **Equitable and Personalized Treatment of Edema Through Wearable Textiles and Machine Learning-Based Pain Assessment.** Liang He (PI) and Sooyeon Jeong, \$192,000. *Institute for Physical Artificial Intelligence (IPAI), Purdue University.*

2023 **Exploratory SAIL Fund. Hacking, Designing, and Making.** Liang He (PI), \$2,667. *Purdue University.*

2023 **Assistive Haptic and Actuated Interface for People with Disability using Modular, Personalized On-body Robots.** Liang He (PI) and Huachao Mao, \$9,538. *Holistic Safety and Security (HSS) Research Impact Area, Purdue University.*

## Honors and Awards

2026 **Special Recognition for Paper Reviews, CHI '26**

2025 **Special Recognition for Paper Reviews, UIST '25**

2025 **Finalist for the 3D Pioneer Challenge Award**

2024 **UIST 2024 Jury Best Poster Award**

2024 **IPAI Postdoctoral Research Award, Purdue University**

2024 **Purdue Polytechnic Institute Faculty Research Award, Purdue University**

2024 **Special Recognitions for Paper Reviews, UIST '24, CHI '24, DIS '24**

2023 **Special Recognitions for Paper Reviews, UIST '23, DIS '23, IMWUT, CHI '23**

2022 **Special Recognition for Paper Reviews, UIST '22, CHI '22**

2021 **Bob Bandes Memorial Honorable Mention Student Teaching Award (top 1%), UW**

2021 **Special Recognition for Paper Reviews, UIST '21**

2020 **Special Recognition for Paper Reviews, UIST '20, CHI '20**

2019 **Winner, CHI '19 SV t-shirt design contest**

2018 **Finalist, Amazon Catalyst Award**

2017 **Best Paper Award (top 1%), CHI '17**

2016 **Conference Travel Funding, Department of Computer Science, University of Maryland**

2016 **Best Late-Breaking Work Paper Award, CHI '16**

2016 **Dean's fellowship, Department of Computer Science, University of Maryland**

2015 **Dean's fellowship, Department of Computer Science, University of Maryland**

2015 **Paper Honorable Mentions Award (top 3%), CHI '15**

2014 **Conference Travel Funding, School of Architecture, Carnegie Mellon University**

2014 **Department Scholarship, School of Architecture, Carnegie Mellon University**

- 2014 **Most Creative Award, UIST '14 Student Innovation Contest**
- 2014 **Winner, CHI '14 SV t-shirt design contest**
- 2013 **Department Scholarship, School of Architecture, Carnegie Mellon University**
- 2012 **Winner, G-Startup Seed Stage, Global Mobile Internet Conference '12**
- 2011 **Winner, Baidu User Experience contest**
- 2011 **Follow-up, Software Design, Microsoft Imagine Cup Local Final**
- 2009 **China National Scholarship (Top 1% nationwide), China**

## Patent/Software Copyright

- 2013 [PA.1] **A Method and System for Children's Tangible Storytelling.**  
*Patent number: 2013100129910*
- 2010 [SC.1] **InkSound: A Pen-based System for Chinese Traditional Painting.**

## Invited Talks

- 2025 **Creative Making through Physical Intelligence.** *HKUST (Guangzhou).*
- 2025 **Creative Making through Physical Intelligence.** *UT Dallas.*
- 2025 **Creative Making through Physical Intelligence.** *UW-Madison.*
- 2023 **Beyond Shape: Creating Interactive 3D Printable Objects.** *UW-Madison.*  
**Beyond Shape: Creating Interactive 3D Printable Objects.** *Purdue University.*  
**Beyond Shape: Creating Interactive 3D Printable Objects.** *Tsinghua University, virtual.*  
**Beyond Shape: Fabricating Kinetic Objects for Interactivity.** *Zhejiang Univ., China.*  
**Beyond Shape: Fabricating Kinetic Objects for Interactivity.** *Duke Kunshan, China.*  
**Beyond Shape: Fabricating Kinetic Objects for Interactivity.** *HCI Seminar, CSAIL, MIT.*
- 2022 **Beyond Shape.** *Georgia Tech.*  
**Beyond Shape.** *Hasso Plattner Institute, Germany.*
- 2021 **Beyond Shape.** *HCIL Brown-Bag Lunch. University of Maryland, College Park.*  
**ModElec.** *CSE Colloquium. University of Washington.*  
**Beyond Shape.** *HCI seminar invited by Ryo Suzuki. University of Calgary. Virtual.*  
**Kinetic Fab Research Overview.** *Lightning Talk. IWHEC 2021 affiliated forum. Virtual.*
- 2020 **3D Printing Electronics.** *HP 3D Print Lab.*  
**Designing, Controlling, and Fabricating In-Place Augmented Structures.** *UIST 2020*

*Doctoral Symposium. Virtual.*

**Designing and Controlling On-Demand 3D Printable Structures to Support the Fabrication for Interactivity.** *DUB Doctoral Colloquium, UW, Seattle.*

2019 **Ondulé.** *Institute of Software, Chinese Academy of Sciences (ISCAS), China.*

**Ondulé.** *HCI Lunch Talk. Stanford, CA.*

**Making 3D-Printed Objects for Interactivity.** *Lightning Talk. UW CSE/MSR Summer Institute – Future of Fabrication, Blaine, WA.*

2018 **Modeling and Fabricating Interactivity and Creativity with Object Properties.** *UW CSE Colloquia – Computational Fabrication. Seattle.*

**Fabricating High-Level Design Specifications with Low-Level Object Properties.** *Industry Affiliates Research Day. UW. Seattle.*

2016 **SqueezAPulse.** *Tech+Design: Interaction Design for a Purpose. UMD, College Park, MD.*

**SqueezAPulse.** *HCIL's 33rd Annual Symposium. UMD, College Park, MD.*

## Guest Lectures/Workshops

2025 [L.9] **Creative Making through Physical Intelligence.** *Computer Aided Design (MECH6303), Department of Mechanical Engineering, Univ. of Texas at Dallas.*

2025 [L.8] **Creative Making through Physical Intelligence.** *Introduction to HCI (CISX82), Department of Computer Science, Univ. of Delaware.*

2024 [L.7] **Intro to Digital Fabrication.** *EECS 493. Department of Computer Science & Engineering. University of Michigan.*

[L.6] **Democratizing Interactivity Prototyping with Digital Fabrication.** *Introduction to HCI, Department of Computer Science, University of Rochester.*

[L.5] **Prototyping Interactivity from Physical to Virtual to Physical.** *Introduction to HCI (CISX82), Department of Computer Science, Univ. of Delaware.*

2022 [L.4] **Prototyping, Prototyping, Prototyping.** *Introduction to HCI (CISX87), Department of Computer Science, Univ. of Delaware.*

[L.3] **Build for Access.** *Introduction to Assistive Technology and Robotics (CNIT 581 AST). Department of Computer Information Technology, Purdue University.*

[W.4] **CSNext Workshop.** *Mentoring four students from underrepresented groups. Computer Science & Engineering, UW.*

2020 [W.3] **3D Printed Electronics with ModElec.** *HP Labs.*

2019 [L.2] **Heuristic Evaluation.** *CSE 440A: Introduction to HCI. CSE, UW.*

2018 [W.2] **Video Making.** *CSE SkillShare Workshop, UW.*

- [W.1] **3D Modeling with Fusion 360.** *CSE 590A: Ubiquitous Computing, CSE, UW.*
- [L.1] **Laser Cutting.** *HCID 521, Human-Computer Interaction & Design, UW.*

## Teaching

- 2025 [TE.20] **CS4352: Introduction to Human-Computer Interaction.** *CS, UT Dallas.*  
*Instructor, 78 enrolled undergrad students*
- 2025 [TE.19] **CGT581: Interactive Prototyping & Digital Fabrication.** *CGT, Purdue. Instructor,*  
*7 enrolled grad students*
- 2025 [TE.18] **CGT532: UX Design Graduate Studio (Cross-Channel).** *CGT, Purdue. Instructor,*  
*13 enrolled grad students, studio-based course*
- 2024 [TE.17] **CGT27108: UX Design Learning Studio - Screen.** *CGT, Purdue.*  
*Instructor, taught 49 undergrad students, studio-based course*
- 2024 [TE.16] **CGT512: Foundational Readings of UX Design.** *CGT, Purdue.*  
*Instructor, taught 14 grad students*
- 2024 [TE.15] **CGT27208: UX Design Learning Studio (Cross-Channel).** *CGT, Purdue.*  
*Instructor, taught 46 undergrad students, studio-based course*
- 2024 [TE.14] **CGT532: UX Design Graduate Studio (Cross-Channel).** *CGT, Purdue.*  
*Instructor, taught 30 grad students, studio-based course*
- 2023 [TE.13] **CGT512: Foundational Readings of UX Design.** *CGT, Purdue.*  
*Instructor, taught 41 grad students*
- 2023 [TE.12] **CGT532: UX Design Graduate Studio (Cross-Channel).** *CGT, Purdue.*  
*Instructor, taught 28 grad students, studio-based course*
- 2022 [TE.11] **CGT116: Geometric Modeling for Visualization and Communication.** *CGT,*  
*Purdue. Instructor, taught 98 undergrad students, statewide and hybrid*
- 2021 [TE.10] **CSE 490: Physical Computing.** *CSE, UW. Remote teaching and hardware*  
*prototyping. Instructor: Jon E. Froehlich*  
  
**Bob Bandes Memorial Honorable Mention Student Teaching Award [Top 1%]**
- 2020 [TE.9] **CSE 590A: Ubiquitous Computing.** *CSE, UW. Course development and remote*  
*teaching. Instructor: Jon E. Froehlich*
- 2019 [TE.8] **CSE 599U: Prototyping Interactive Systems.** *CSE, UW.*  
*Instructor: Jon E. Froehlich*
- [TE.7] **CSE 440A: Introduction to HCI.** *CSE, UW.*  
*Instructor: Nigini Oliveira*
- 2018 [TE.6] **CSE 440A: Introduction to HCI.** *CSE, UW.*  
*Instructor: Nigini Oliveira*
- [TE.5] **CSE 590A: Ubiquitous Computing.** *CSE, UW. Course development*

*Instructor: Jon E. Froehlich*

[TE.4] **HCID 521: Prototyping Studio.** *HCID, UW. Course development*  
*Instructors: Jon E. Froehlich and Jennifer Mankoff*

2016 [TE.3] **CMSC 250: Discrete Structures.** *CS. UMD, College Park.*  
[TE.2] **CMSC 132: Object-Oriented Programming II.** *CS. UMD, College Park.*  
2015 [T.1] **CMSC 131: Object-Oriented Programming I.** *CS. UMD, College Park.*

## Services

### *Program Committee*

2026 **ASSETS 2026 Program Committee, Associate Chairs, papers**  
2026 **UIST 2026 Program Committee, Associate Chair, papers**  
2026 **DIS 2026 Program Committee, Associate Chair, Artifacts & Systems subcommittee**  
2025 **CHI 2026 Program Committee, Associate Chair, Developing Novel Devices subcommittee**  
2025 **UIST 2025 Program Committee, Associate Chair, papers**  
2025 **TEI 2026 Paper Co-chair, work-in-progress**  
2025 **CHI 2025 Program Committee, Associate Chair, Blending Interaction: Engineering Interactive Systems & Tools subcommittee**  
2024 **TEI 2024 Program Committee, Associate Chair, papers**  
2024 **UIST 2024 Program Committee, Associate Chair, papers**  
2024 **DIS 2024 Program Committee, Associate Chair, papers and pictorials**  
2024 **ASSETS 2024 Program Committee, Associate Chair, papers, posters, and demos**  
2024 **SIGGRAPH 2024 Posters Jury Committee**  
2024 **SIGGRAPH 2024 Emerging Technologies Jury Committee**  
2024 **CHI 2024 Program Committee, Associate Chair, Blending Interaction: Engineering Interactive Systems & Tools subcommittee**  
2024 **CHI 2024 Student Design Competition Review Committee**  
2023 **ASSETS 2023 Program Committee, Associate Chair, papers, posters, and demos**  
2023 **DIS 2023 Program Committee, Associate Chair, papers and pictorials**  
2023 **Invited Guest Editor for Journal - CCF Transactions on Pervasive Computing & Interaction**  
2023 **IDC 2023 Program Committee, Associate Chair, papers**  
2022 **ASSETS 2022 Program Committee, Associate Chair, papers, posters, and demos**

- 2021 **ACHI 2021 Program Committee, Associate Chair, papers**
- 2021 **IDC 2021 Program Committee, Associate Chair, work-in-progress**
- 2021 **CHI 2021 Program Committee, Associate Chair, late-breaking work**
- 2020 **CHI 2020 Program Committee, Associate Chair, late-breaking work**
- 2019 **CHI 2019 Program Committee, Associate Chair, late-breaking work**

### ***Organizing Committee***

- 2025 **TEI 2026 Paper Co-chair, work-in-progress**
- 2024 **Student Innovation Contest co-chair, UIST 2024**
- 2023 **Posters & Demos co-chair, ASSETS 2023**
- 2023 **Experience Reports co-chair, ASSETS 2023**
- 2023 **Proceedings co-chair, UIST 2023**
- 2022 **Proceedings co-chair, UIST 2022**
- 2022 **Web and Graphic Design co-chair, ASSETS 2022**
- 2019 **Design and Web co-chair, UIST 2019**

### ***Reviewing***

250+ papers, **17 special recognitions for excellent review**

- 2025 **SIGGRAPH 2025, IMWUT (Feb), UIST '25, CHI '26**
- 2024 **UIST '24, CHI '25, DIS '24, TEI '25, SIGGRAPH '24, ASSETS '24, ISMAR '24**
- 2023 **CHI '24, SCF '23, IDC '23, ASSETS '23, DIS '23, UIST '23, IEEE VR '24**
- 2022 **CHI '23, UIST '22, ASSETS '22, IEEE VR '23, IMWUT (November)**
- 2021 **CHI '22, UIST '21, DIS '21, SCF '21, CSCW (April), AHCI '21**
- 2020 **CHI '21, UIST '20, DIS '20, SCF '20**
- 2019 **CHI '20, UIST '19, WAC '19**
- 2018 **CHI '19**
- 2017 **CHI '18, TEI '18**
- 2016 **CHI '17, TEI '17, MobileHCI '16**
- 2015 **CHI '16**

### ***Other Services***

- 2025 **Session Chairs, UIST 2025**
- 2024 **Session Chairs, UIST 2024**
- 2023 **Session Chair, CHI 2023**
- 2022 **Session Chair, UIST 2022**
- 2021 **Session Chair, UIST 2021**
- 2017 **Student Volunteer, TEI 2017**
- 2015 **Student Volunteer, CHI 2015**
- 2014 **Student Volunteer, UIST 2014**
- 2014 **Student Volunteer, CHI 2014**
- 2012 **Student Assistant, the first China Symposium on HCI**

## Outreach

### **Collaborating with Seeed Studio to organize UIST 2024 Student Innovation Contest**

*Selected and created a custom hardware kit – Gen-M Kit – that contains over 80 programmable modules for physical computing and distributed the kits to eight student teams around the world.*

### **Leading the creation and maintenance of FabGalaxy (since 2018)**

*FabGalaxy is an online interactive visualization repository that provides a quick entry to fabrication research in human-computer interaction and computer graphics. This platform is hosted on the MIT's online repository for personal fabrication research which was created and maintained by HCI Engineering group, MIT CSAIL.*

## Press Coverages

- 2025 **Researchers Create AI Tool To Help Sight-Impaired Programmers.** *UTD News - Science & Technology.* [Link](#)
- 2025 **New AI Tool opens 3D modeling to blind and low-vision programmers.** *Michigan News. University of Michigan.* [Link](#)
- 2024 **Meet MobiPrint: A Mobile 3D Printer that Can Automatically Measure a Room and Print to the Specs.** *Tech Briefs.* [Link](#)
- 2024 **This Mobile 3D Printer Can Print Directly on Your Floor.** *IEEE Spectrum.* [Link](#)
- 2024 **Meet MobiPrint: The smart 3D printer that can upgrade your home instantly.** *TechXplore.* [Link](#)
- 2024 **From accessibility upgrades to a custom cat-food bowl, this mobile 3D printer can autonomously add features to a room.** *UW News.* [Link](#)

2024 **3D printing on the move: UW device can map a room and print custom items in desired space.** *GeekWire.* [Link](#)

## Students

### PhD Committees

2025–Present **Yili (Angel) Wen.** *Ph.D. in Computer Science at UT Dallas*  
2025–Present **Difan (Bobby) Jia.** *Ph.D. in Computer Science at UT Dallas*  
2024–Present **Fu-Chia Yang.** *Ph.D. in Technology at Purdue*  
2023–Present **Ali Baigelenov.** *Ph.D. in Technology at Purdue*  
2023–Present **Min Soo Choi.** *Ph.D. in Technology at Purdue*  
2022–2023 **Dixuan Cui.** *Now Assistant Professor at Sam Houston State University*

### Advisees

2025–Present **Yili (Angel) Wen.** *PhD in CS at UT Dallas.*  
2025–Present **Difan (Bobby) Jia.** *PhD in CS at UT Dallas.*  
2025–Present **Junke Zhao.** *Research Associate. M.S. in Computational Design from CMU.*  
2024–Present **Aezaz Ali.** *M.S. in Gaming at Purdue.*  
2022–Present **Hsuanling Lee.** *Research Associate. B.S. in Computer Engineering from Purdue.*  
2023–2025 **Amy Yu.** *M.S. in Information Visualization at Purdue.*  
2024–2025 **Thomas Carlock.** *M.S. in UX Design at Purdue.*  
2024–2025 **Jasmine Li.** *Senior in UX Design at Purdue.*  
2024 **Liuyi Chen.** *Visiting undergraduate student in Computer Science at HUST.*  
2023 **Riddhi Chaudhari.** *M.S. in User Experience Design at Purdue.*  
2023 **Prithvi Manjunatha.** *M.S. in User Experience Design at Purdue.*  
2023 **Chenxi Yang.** *Senior in Computer Science and Technology at Tsinghua University.*  
2023 **Jacqueline Dong.** *M.F.A. in Communications Design at Pratt Institute.*  
2023 **Srishti Shekhar Agrawal.** *M.S. in User Experience Design at Purdue.*  
2022 **Liwen He.** *M.S. in Industrial Design at Beihang University, China.*  
2022 **Yifan Li.** *Senior in Architecture at Southeast University, China.*  
2021–2022 **Daniel Campos Zamora.** *Ph.D. in CSE at UW.*

2021 **Hongnan Lin.** *Ph.D. in Design at Georgia Tech; now postdoc at ISCAS.*

2020–2021 **Yueqian Zhang.** *Undergraduate in CSE at UW; now engineer at Roblox.*

2020–2021 **Xia Su.** *M.S. in Architecture at Tsinghua; now Ph.D. in CSE at UW.*

2020–2021 **Xiyuan Shen.** *Undergraduate in Media Art at Tsinghua; now Ph.D. in CSE at UW.*

2020–2021 **Arjun Simha.** *High school student; now undergrad in EE at UW.*

2019–2021 **Jessica Chin.** *Undergraduate in Psychology at UW; now at Meta.*

2020 **Yawen Zheng.** *Undergraduate in Media Art at Tsinghua; now M.S. at Tsinghua.*

2020 **Yuebing Liang.** *M.S. in Architecture at Tsinghua; now Ph.D. at Hong Kong Univ.*

2019 **Venkatesh Potluri.** *Ph.D. in CSE at UW; now Assistant Professor at UMich.*

2019 **Sophie Tian.** *Undergrad in CSE at UW; now software engineer at Microsoft.*

2018–2019 **Michelle Lin.** *Undergrad in CSE at UW; now grad in CSE at UW.*

2017 **Joshua Land.** *Undergrad in Mech Engineering at UMD; now engineer at Appian.*

2012 **Muyan Li.** *Undergrad at Beihang; now software engineer at UiPath.*

2012 **Yang Zhang.** *Undergrad at Beihang; now Assistant Professor at UCLA.*

2012 **Keqin Dou.** *Undergrad at Univ. of Science and Technology Beijing; now regional director at Fintopia.*